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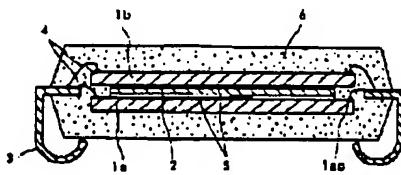
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(54) RESIN-SEALED TYPE SEMICONDUCTOR
DEVICE

(57) Abstract:

PURPOSE: To simplify a process by joining a junction plate with a circuit forming surface of a first semiconductor element via an insulating member to be wire-bonded and by joining a non-circuit-forming surface of a second semiconductor element to the opposite side of the junction plate via an insulating member to be wire-bonded.

CONSTITUTION: While a semiconductor element 1a with a circuit forming surface facing upward is mounted, a lead frame comprising an assembly of a junction plate 2 having smaller size than the semiconductor element 1a and having insulating members 5 on both sides and a lead 3 is mounted and joined so that an electrode pad lap is exposed. Then, a wire 4 is used to electrically connect the semiconductor element 1a to the lead 3. Then, a semiconductor element 1b is mounted and joined from an upper part of the junction plate 2 with a circuit forming surface facing upward, and the wire 4 is used to electrically connect the semiconductor element 1b to the lead 3. The assembly is sealed by resin 15 and molded with an unnecessary part of the lead 3 cut off. Thus, a manufacture process can be simplified.



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